What is claimed is:

1. A semiconducting device comprising:

an interposer that includes a fold which divides the interposer into a first section and a second section;

a first die attached to a first surface of the interposer at the first section and the second section;

a contact attached to the first surface of the interposer at the first section and the second section;

a second die attached to a second surface of the interposer, the second die being stacked onto the first die and electrically coupled to the first die by the contact and conductive paths that are part of the interposer.

2. The semiconducting device of claim 1, wherein the contact is a solder column.

3. The semiconducting device of claim 1, wherein the first die is encapsulated on the first surface of the interposer.

4. The semiconducting device of claim 1, wherein the second die is encapsulated on the second surface of the interposer.

5. The semiconducting device of claim 1, further comprising a plurality of contacts that are each attached to the first surface of the interposer at the first section and the second section.

6. The semiconducting device of claim 5, wherein the fold is on one side of the first die and at least one of the contacts is on an opposite side of the first die.

7. The semiconducting device of claim 5, wherein at least one of the contacts is on each side of the first die.

8. A method comprising:

securing a first die to a first section of an interposer, the interposer including a first conductor and a second conductor on a first surface of the interposer;

folding the interposer to secure the first die to a second section of the interposer and to connect the first conductor to the second conductor to form a contact; and

securing a second die to a second surface of the interposer such that the first and second dice are stacked one on top of another and electrically coupled by the interposer and the contact.

9. The method of claim 8, wherein folding the interposer to connect the first conductor to the second conductor includes soldering the first conductor to the second conductor.

10. The method of claim 8, wherein folding the interposer to secure the first die to a second section of the interposer includes placing an adhesive on the first die and connecting the second section of the interposer to the adhesive.

11. The method of claim 8, wherein securing a first die to a first section of an interposer includes soldering the first die to the interposer.

12. The method of claim 8, wherein securing a second die to a second surface of the interposer includes soldering the second die to the second surface of the interposer.

13. The method of claim 8, wherein the fold is on one side of the first die such that folding the interposer includes forming a contact on an opposing side of the first die.

14. The method of claim 8 wherein the interposer includes a plurality of conductors on the first surface of the interposer such that folding the interposer includes connecting each of the conductors to another conductor to form a plurality of contacts that extend from the first surface of the interposer between the first section and the second section.

15. The method of claim 14, wherein the fold is on one side of the first die such that folding the interposer includes forming at least one contact on an opposing side of the first die.

16. The method of claim 14, wherein the fold is on one side of the first die such that folding the interposer includes forming at least one contact on each side of the first die except for the one side of the first die.

17. The method of claim 14, wherein folding the interposer includes forming at least one contact on each side of the first die.

18. An electronic system comprising:

a bus;

a memory coupled to the bus;

a semiconducting device that is electrically connected to the bus, the semiconducting device having an interposer that includes a fold which divides the interposer into a first section and a second section, the semiconducting device further including a first die and a contact that are each attached to the first surface of the interposer at the first section and the second section, the semiconducting device further including a second die attached to a second surface of the interposer, the second die being stacked onto the first die and electrically coupled to the first die by the contact and the interposer.

19. The electronic system of claim 18, further comprising a plurality of contacts that are each attached to the first surface of the interposer at the first section and the second section.

20. The electronic system of claim 18, further comprising a voltage source electrically coupled to the semiconducting device.